

PolarHT[™] HiPerFET IXFN 140N20P Power MOSFET

N-Channel Enhancement Mode Fast Intrinsic Diode



$V_{\scriptscriptstyle DSS}$	=	200	V
I _{D25}	=	115	Α
R _{DS(on)}	≤	18	$m\Omega$
t _{rr}		150	

Symbol	Test Conditions	Maximum Ratings		
V _{DSS}	$T_J = 25^{\circ}C \text{ to } 175^{\circ}C$	200	V	
\mathbf{V}_{DGR}	$T_{_{\rm J}} = 25^{\circ}\text{C} \text{ to } 175^{\circ}\text{C}; R_{_{\rm GS}} = 1 \text{M}\Omega$	200	V	
V _{gs}	Continuous	±20	V	
$V_{\rm GSM}$	Transient	±30	V	
I _{D25}	T _C = 25°C	115	А	
I _{D(RMS)}	External lead current limit	100	Α	
I _{DM}	$T_{\rm C} = 25^{\circ}$ C, pulse width limited by $T_{\rm JM}$	280	Α	
I _{AR}	T _C = 25°C	60	А	
E _{AR}	$T_{C} = 25^{\circ}C$	100	mJ	
E _{AS}	$T_{c} = 25^{\circ}C$	4	J	
dv/dt	$I_{S} \leq I_{DM}, di/dt \leq 100 A/\mu s, V_{DD} \leq V_{DSS},$ $T_{J} \leq 150 ^{\circ} C, R_{G} = 4 \Omega$	10	V/ns	
$\overline{P_{D}}$	T _C = 25°C	680	W	
$T_{\rm J}$		-55 + 175	°C	
T		175	°C	
T _{stg}		-55 +150	°C	
T_L	1.6 mm (0.062 in.) from case for 10 s	300	°C	
V _{ISOL}	50/60 Hz, RMS, 1 minute	2500	V~	
M _d	Terminal torque Mounting torque	1.13/10 1.13/10	Nm/lb.in. Nm/lb.in.	
Weight		30	g	

_	G	S
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miniBLOC, SOT-227 B (IXFN)

E153432

G = Gate D = Drain S = Source

Either source tab S can be used forsource current or Kelvin gate return.

Features

- International standard package
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
- easy to drive and to protect
- Fast intrinsic diode

Symbol	Test Conditions				ristic Values	
$(1_{J} = 25^{\circ}C,$	unless otherwise specified)		Min.	Тур.	Max	·
BV _{DSS}	V_{GS} = 0 V, I_{D} = 250 μA		200			V
V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 4 \text{ mA}$		2.5		5.0	V
GSS	$V_{GS} = \pm 20 V_{DC}, V_{DS} = 0$				±100	nA
I _{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0 V$	T _J = 150°C			25 250	μA μA
R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_{D} = 70 \text{ A}$ $V_{GS} = 15 \text{ V}, I_{D} = 140 \text{A}$ Pulse test, $t \le 300 \mu\text{s}, \text{ duty}$	cycle d ≤2%		14	18	m Ω

Advantages

- Easy to mount
- Space savings
- High power density

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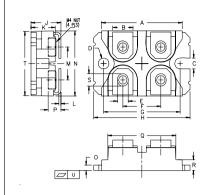
Symbo	ol	Test Conditions (T ₁ = 25°			ristic Values rise specified)
			Min.	Тур.	Max.
g_{fs}		$V_{DS} = 10 \text{ V}; I_{D} = 70 \text{ A}$	50	84	S
\mathbf{C}_{iss})			7500	pF
\mathbf{C}_{oss}	}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		1630	pF
C _{rss}	J			280	pF
$\mathbf{t}_{d(on)}$)			30	ns
t _r		$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \text{ V}_{DSS}, I_{D} = 70 \text{ A}$		35	ns
$\mathbf{t}_{d(off)}$	($R_{\rm G} = 3.3 \Omega$ (External)		150	ns
t _f)			90	ns
$\mathbf{Q}_{\mathrm{g(on)}}$)			240	nC
Q_{gs}	}	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \text{ V}_{DSS}, I_{D} = 70 \text{ A}$		50	nC
\mathbf{Q}_{gd}	J			110	nC
R _{thJC}					0.22 K/W
$\mathbf{R}_{\mathrm{thCS}}$				0.05	K/W

Source-Drain Diode

Characteristic Values (T₁ = 25°C, unless otherwise specified)

Symbol	Test Conditions M	in. Typ.	Max.	
I _s	$V_{GS} = 0 V$		140	Α
I _{SM}	Repetitive		280	Α
V _{SD}	$I_F = I_S$, $V_{GS} = 0$ V, Pulse test, t ≤ 300 μ s, duty cycle d ≤ 2 %		1.5	V
$\left\{egin{array}{c} \mathbf{t}_{rr} & \\ \mathbf{Q}_{RM} & \\ \mathbf{I}_{RM} & \end{array}\right\}$	$I_F = 25 \text{ A}$ $-\text{di/dt} = 100 \text{ A/}\mu\text{s}$ $V_R = 100 \text{ V}$	0.6	200	ns μC Α

SOT-227B miniBLOC



	INCH	IF C	MTLLTM	1ETERS
MYS	MIN	MAX	MIN	MAX
Α	1,240	1.255	31.50	31.88
В	.307	.323	7.80	8.20
С	.161	.169	4.09	4.29
D	.161	.169	4.09	4.29
E	.161	.169	4.09	4.29
F	.587	.595	14.91	15.11
G	1.186	1.193	30.12	30.30
Н	1.496	1.505	38.00	38.23
J	.460	.481	11.68	12.22
K	.351	.378	8.92	9.60
L	.030	.033	0.76	0.84
М	.496	.506	12.60	12.85
N	.990	1.001	25.15	25.42
0	.078	.084	1.98	2.13
Р	.195	.235	4.95	5.97
Q	1.045	1.059	26.54	26.90
R	.155	.174	3.94	4.42
S	.186	.191	4.72	4.85
T	.968	.987	24.59	25.07
U	002	.004	-0.05	0.1



Fig. 1. Output Characteristics @ 25°C

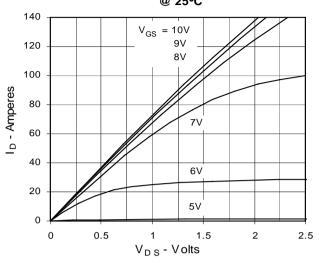


Fig. 3. Output Characteristics @ 150°C

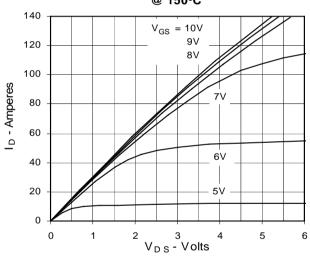


Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 70A$ Value vs. Drain Current

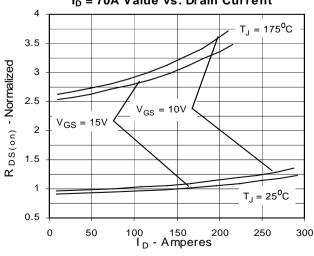


Fig. 2. Extended Output Characteristics @ 25°C

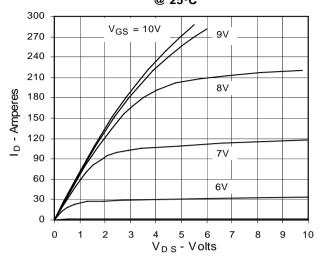


Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 70A$ Value vs. Junction Temperature

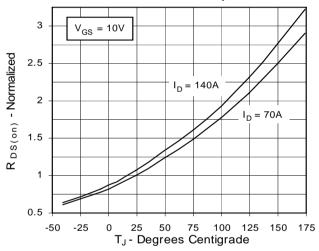
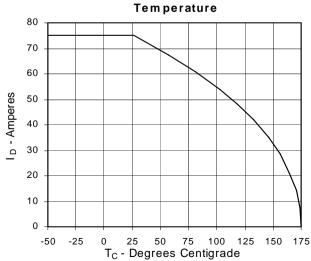
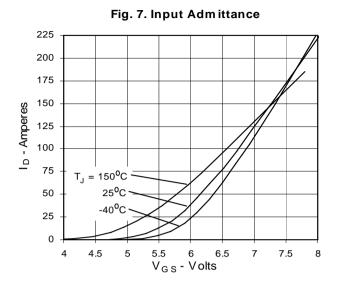
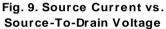


Fig. 6. Drain Current vs. Case
Temperature









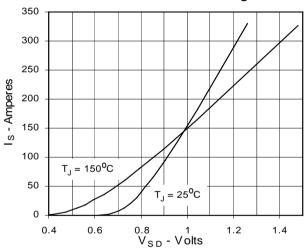


Fig. 11. Capacitance

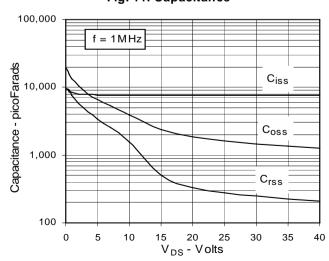


Fig. 8. Transconductance

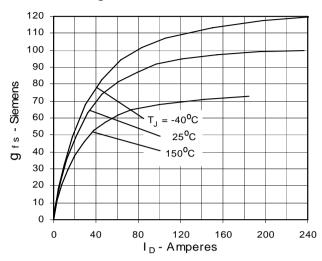


Fig. 10. Gate Charge

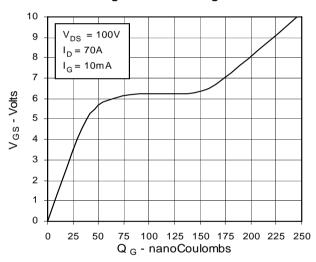
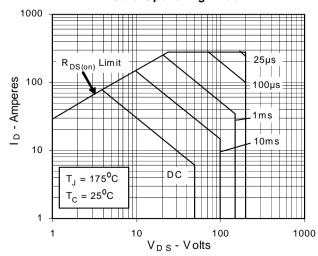


Fig. 12. Forward-Bias Safe Operating Area



IXYS reserves the right to change limits, test conditions, and dimensions.



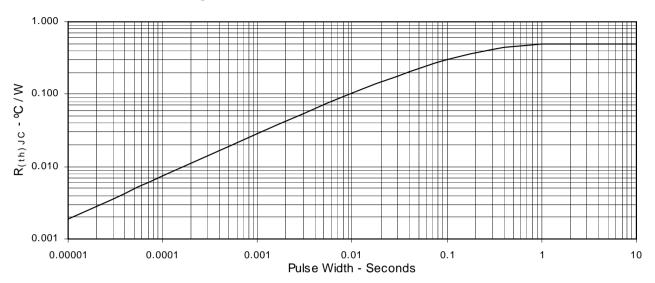


Fig. 13. Maximum Transient Thermal Resistance

